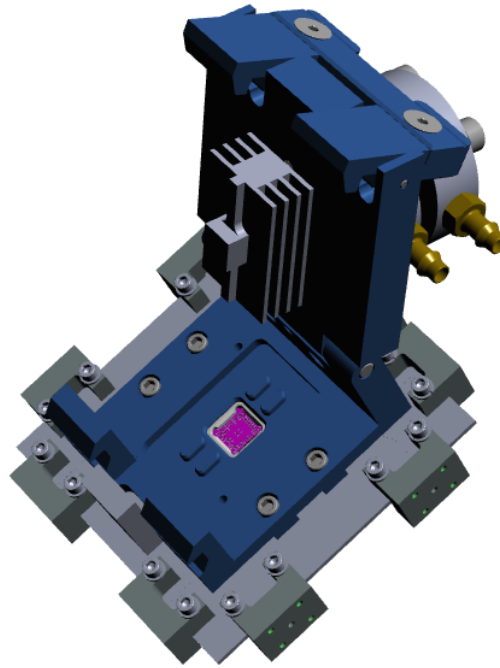




Recent design wins for Paricon Test sockets in Germany, May 2019

By using the very thin PariPoser conducting elastomer there is NO measurable degradation of RF performance notable. The DUTs are connected very reliable down to 0.1mm pitch and up to 100GHz+.

Example1:



DUT: 30GHz 6x6x0.6mm BGA, 0.5mm pitch, 1300mW dissipated power

Solution: Testsocket F09 featuring pneumatic pressure activation with active cooling by forced air flow. NO noted RF performance difference between soldered down and pressed down DUT. DUT replacement within seconds and w/o any tool/solder

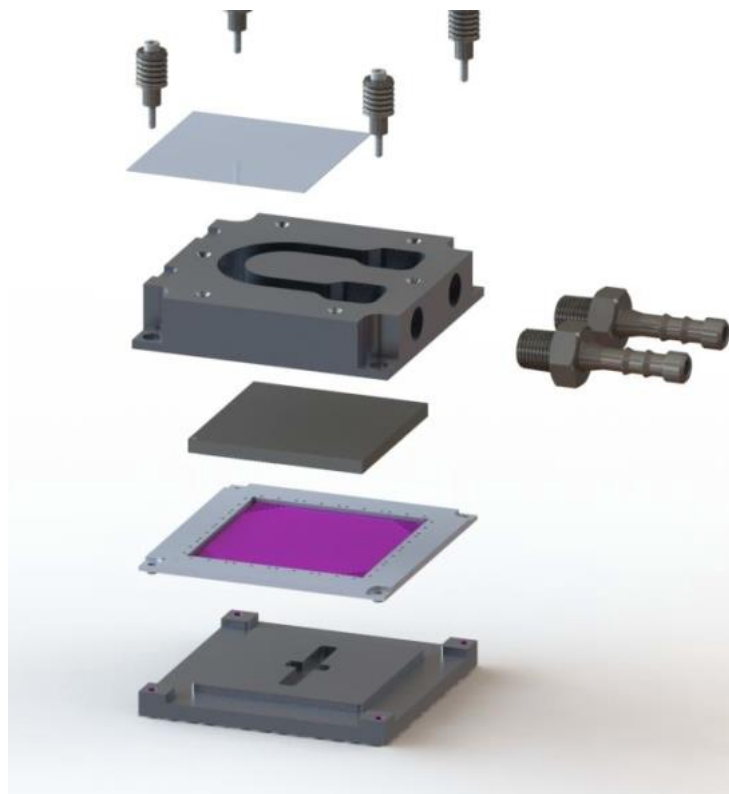
Example2:



DUT: 1.5x2.5x0.6mm LGA, 0.5mm pitch, 11contacts, solder stop between terminals

Solution: Testsocket F14 with manual lid and pre-set down force. Contactor can be used without top-lid in production test environment with >>100k cycles: Contactor available with "PariPoser only" or with 0.4mm „Bullet Pins”.

Example3:



Device: FPGA 45x45mm, 0.8mm pitch, 2000BGA contacts, 100W dissipated power

Solution: Application socket F18, long term stable BGA contacting by crown contacts, thermal optimization with Indium plates, top-lid available with liquid cooling alternatively as massive aluminum/copper lid for attachment of heat pipes / peltier elements